

PRODUCT SPECIFICATION

CKM 1251 & 1253 HIGH CURRENT SERIES

WIRE TO BOARD 1.25 mm PITCH CONNECTOR

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1. SCOPE

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size for wire.

2. APPLICABLE STANDARDS

EIA-364-18 Methods for test of connectors for electronic equipment MIL-STD-202 JIS C5402 UL 1977

3. APPLICABLE SERIES NO: 1251 & 1253 SERIES

Product Name	Part No.
Housing	1251H-XP-X-HC-HF
	1251HM-XP-X-HC-HF
Terminal	1251T0H-XX
	1251TM0H-XX
Wafer Assembly ST. (SMT)	
Wafer Assembly RA. (SMT)	1253WE-XP-A-HC-HF

X: Refer to the drawing

4. PRODUCT SHAPE, DIMENSIONS & MATERIALS *See attached drawings.

5. ACCOMMODATED P.C. BOARD

5.1 Thickness: 1.0 mm (.039 ")~1.2mm (.047 "), 1.6 mm (.063 ") 5.2 P.C. Board Layout: See attached drawings

6. RATINGS

6.1 Current rating: 2.0A MAX. AC/DC (AWG #28)

6.2 Voltage rating: 125V AC, DC

6.3 Temperature range: -40° C to $+105^{\circ}$ C

6.4 Applicable wire: AWG #32 to #28, Insulation O.D.: 1.0mm Max.

7. PERFORMANCE REQUIREMENTS AND TEST DESCRIPTIONS

The product is designed to meet the electrical, mechanical and environmental performance Requirements as specifics in **8. REQUIREMENTS.**

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		IREMENTS AN							
Т	EST ITEM	REQUI	REMENT		PROCEDUR	E			
8.1	Examination of Product	-	nents of product hysical damage.						
	1	ELEC	TRICAL REQU	IREMI	ENT				
8.2	Contact Resistance	20mΩ Max (Init 40mΩ Max (Fin	,	Mate c 20mV Mated (Based	rcuit,				
8.3	Insulation Resistance	100MΩ Min		Betwee (Based	onnectors, apply 500 en adjacent terminal upon JIS C5402 5.2 Iethod 302 Condition	or groun 2 / MIL-S			
8.4	Dielectric Withstanding Voltage	No breakdown		Mate connectors, apply 250V A.C. for 1 minute between adjacent terminal or ground. (Based upon JIS C5402 5.1/ MIL-STD-202 Method 301)					
	I	MECH	ANICAL REQU	JIREM	ENT				
8.5	Terminal crimp Tensile strength	See Item 9.		Fix the out for 25±3 m *Crimp	of				
8.6	Pin Retention Force	0.5kgf Min.		Apply rate of	ed				
8.7	Terminal / Housing Retention Force	0.5kgf Min.		Apply axial pull out force at the speed rate of 25±3 mm/minute on the termina assembly in the housing					
	Mating & Un-mating force	See Item 11.		Insert and withdraw connector at speed 25 ± 3 mm per minute					
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		of initial	Co	nnector shall be subjecte	ed to 30 o	cycles	
8.9	Durability	Dielectric Withs Voltage: To pass Para 9.4 * See Item 11.	-		edly		
8.10	Pin retention force (For Header)	0.5kgf Min.		Pus 25=	ise at speed		
		ENVIRO	NMENTAL REÇ	QUI	REMENTS		
0.11	8.11 Temperature Maximum Temp rise 30°C above amb						
8.12	Vibration	o damage; ace: 40mΩ Max; max.	Sw Du	nplitude: 0.75mm eep Time: 10-55-10 Hz/ ration: 2 Hours in each 2 ased upon MIL-STD-202	X,Y,Z ax		
8.13	Mechanical 3 Mechanical 3 Shock 3 Shock 3 No physical dam & No electric dis greater than 1 μ & Contact resist 40 m Ω Max Aft		iscontinuity sec. shall occur tance:	Sul (pe 11 shc app per spe loa ma	of		
8.14	Vo Physical dan Heat aging & Contact resist 40 m Ω Max Af		tance:	ance: oven for 96±4 hours at 10			an
8.15	Cold Resistance	No physical dar & Contact resist 40 m Ω Max Af	tance:		te connectors: Duration mperature: $-40 \pm 2^{\circ}C$: 96 hou	·s;
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8.16	Humidity	No physical damage & Contact resistance: 40 m Ω Max after test & Insulation resistance: 10 MΩ Min; & Dielectric withstanding voltage No breakdown	Subject mated plug and connector, soldered to P.C. Board, to relative humidity $90 \sim 95\%$ RH and a temperature of 60° C $\pm 2^{\circ}$ C relative humidity for 96 hour. It shall be subjected to standard atmospheric condition for 1 hour after which measurements shall be made.
8.17	Temperature cycling	Appearance: No damage Contact resistance: Less than twice of initial	Mated connector shall be set to temperature cycling for 5 cycles of which 1 cycle consists of: a) $+25^{\circ}C \sim 3$ minutes b) $-25^{\circ}C \sim 30$ minutes c) $+25^{\circ}C \sim 3$ minutes d) $+85^{\circ}C \sim 30$ minutes (Based upon JIS C5402 7.2)
8.18	Salt spray	Appearance: No damage Contact resistance: Less than twice of initial	Mated connector shall be placed on a salt spray chamber on the following conditions. (Based upon JIS C5402 7.1 / MIL-STD-202 Method 101 Condition B) Salt Solution Density : 5±1% Temperature : 35±2°C Duration : 8 Hours
8.19	Solder ability	Solder coverage: 95% Min.	Subject the test area of contacts into the flux for 5-10 sec. And then into solder bath, Temperature at $245 \pm 5^{\circ}$ C for 3 ± 0.5 sec.
8.20	Resistance to Reflow Soldering Heat	No damage	Refer Reflow temperature profile See Figure 2.
8.21	Soldering iron method	No damage	Apply solder iron in solder tail Temperature: 350±10°C, 3~4 sec.

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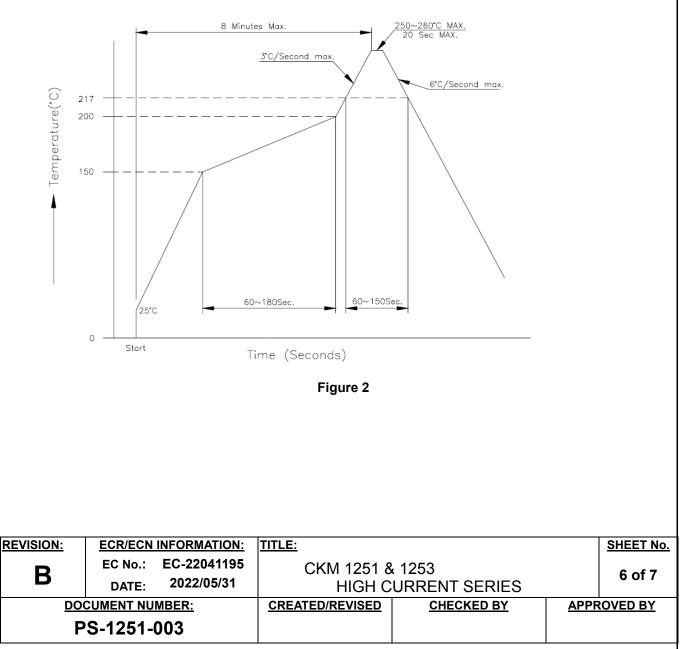
9. Crimping Specification

1251T0H-XX								
Wire Size(A	AWG)	#28	#32					
1. CONDUCTOR (mm)	CRIMP WIDTH	0.85±0.05						
	CRIMP HEIGHT	0.52~0.62	0.47~0.57	0.42~0.52				
2 INSULATION (mm)	CRIMP WIDTH	1.00	1.00	0.95				
2. INSULATION (mm)	CRIMP HEIGHT	1.15	1.00	0.85				
CRIMP STR	ENGTH	1.0Kgf (MIN)	0.5Kgf (MIN)	0.3Kgf (MIN)				
		Eiguro 1		•				

Figure 1

10. Recommended Reflow Temperature Profile:

Using Lead-Free Solder Paste





UNIT: Kgf Withdrawal (MIN.) Insertion (MAX.) Circuits Initial 10th Initial 30th 0.23 0.18 2 2.0 0.28 3 2.5 0.30 0.25 0.20 4 3.0 0.33 0.28 0.23 5 3.5 0.38 0.33 0.28 0.43 0.38 0.33 6 4.0 0.48 0.38 7 4.5 0.43 0.53 8 5.0 0.48 0.43 9 5.5 0.56 0.51 0.46 10 0.59 6.0 0.54 0.49

11. MATING AND UN-MATING FORCE (REMOVE LATCH)

12. PRODUCT QUALIFICATION AND REQUALIFICATION TEST SEQUENCE

		Test Group											
Test or Examination	Α	В	С	D	Е	F	G	Н	Ι	J	Κ	L	Μ
	Test Sequence (a)												
Examination of Product	1,8	1,7	1	1	1	1	1,3	1,5	1,5	1,5	1,5	1,3	1,3
Contact Resistance	2,7	2,6						2,4	2,4	2,4	2,4		
Insulation Resitance		3,5											
Dielectric withstanding Voltage	3,6												
Terminal crimp Tensile strength			2										
Terminal / Housing Insertion Force (For Plug)				2									
Mating & Un-mating force	4												
Durability	5												
Pin retention force (For Header)					2								
Temperature Rise						2							
Vibration							2						
Heat aging								3					
Cold Resistance									3				
Humidity		4											
Temperature cycling										3			
Salt spray											3		
Solder ability												2	
Resistance to Reflow heat													2
Sample Size	5	5	5	5	5	5	5	5	5	5	5	5	5
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